



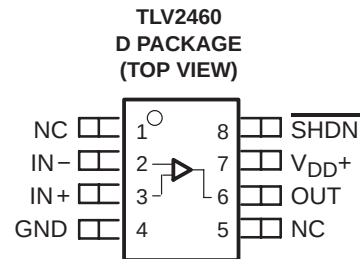
THE DATASHEET OF TLV2462AMDREP

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of –55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product Change Notification**
- **Qualification Pedigree†**
- **Rail-to-Rail Output Swing**
- **Gain Bandwidth Product . . . 6.4 MHz**
- **±80 mA Output Drive Capability**
- **Supply Current . . . 500 µA/channel**
- **Input Offset Voltage . . . 100 µV**
- **Input Noise Voltage . . . 11 nV/√Hz**
- **Slew Rate . . . 1.6 V/µs**
- **Micropower Shutdown Mode (TLV2460/3) . . . 0.3 µA/Channel**
- **Universal Operational Amplifier EVM**

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.



description

The TLV246x is a family of low-power rail-to-rail input/output operational amplifiers specifically designed for portable applications. The input common-mode voltage range extends beyond the supply rails for maximum dynamic range in low-voltage systems. The amplifier output has rail-to-rail performance with high-output-drive capability, solving one of the limitations of older rail-to-rail input/output operational amplifiers. This rail-to-rail dynamic range and high output drive make the TLV246x ideal for buffering analog-to-digital converters.

The operational amplifier has 6.4 MHz of bandwidth and 1.6 V/µs of slew rate with only 500 µA of supply current, providing good ac performance with low power consumption. Devices are available with an optional shutdown terminal, which places the amplifier in an ultralow supply current mode ($I_{DD} = 0.3 \mu\text{A/ch}$). While in shutdown, the operational-amplifier output is placed in a high-impedance state. DC applications are also well served with an input noise voltage of 11 nV/√Hz and input offset voltage of 100 µV.

ORDERING INFORMATION†

T _A	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	D	Tape and reel	TLV2462AQDREP	2462AE
	D	Tape and reel	TLV2463AQDREP	V2463AQE
–55°C to 125°C	D	Tape and reel	TLV2462AMDREP	2462AM
	D	Tape and reel	TLV2464AMDREP	V2464AME
	PW	Tape and reel	TLV2464AMPWREP	2464AME

† Some of the TLV246x family, along with packaging options, are in the **Product Preview** stage of development. Contact the local Texas Instruments sales office for availability.

‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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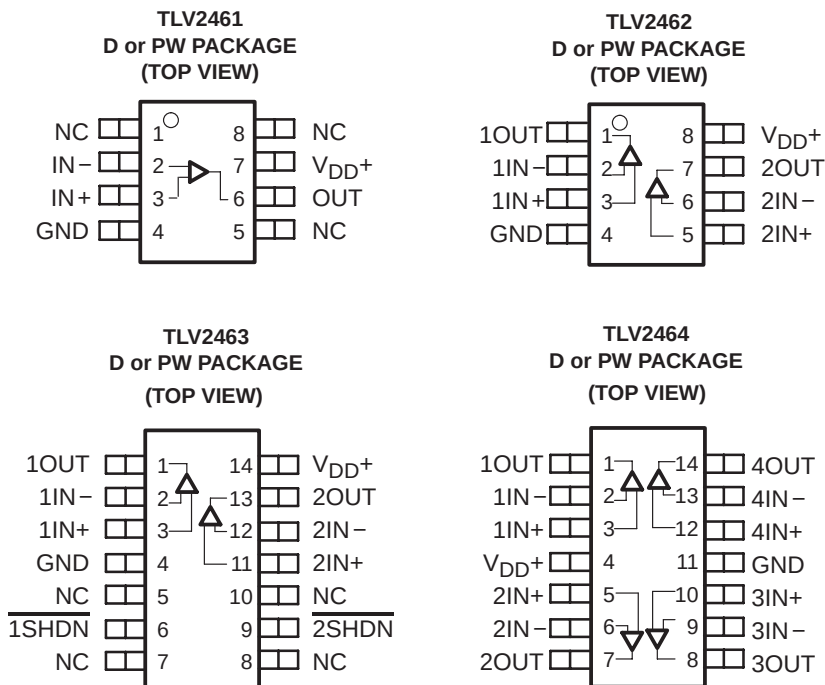
TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP

FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

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TLV246x PACKAGE PINOUTS



NC – No internal connection

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V_{DD} (see Note 1)	6 V
Differential input voltage, V_{ID}	- 0.2 V to $V_{DD} + 0.2$ V
Input current, I_I (any input)	± 200 mA
Output current, I_O	± 175 mA
Total input current, I_I (into V_{DD+})	175 mA
Total output current, I_O (out of GND)	175 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A	-55°C to 125°C
Maximum junction temperature, T_J	150°C
Storage temperature range, T_{stg}	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential voltages, are with respect to GND.

THERMAL RESISTANCE TABLE

PACKAGE	θ_{JC} (°C/W)		θ_{JA} (°C/W, 0 Air Flow)	
	High K	Low K	High K	Low K
D (8)	39.4	42.4	97.1	165.5
D (14)	51.5	53.7	86.2	133.5
PW (8)	65.1	69.4	149.4	230.5
PW (14)	45.8	46.6	111.7	131.4

NOTE: Thermal resistances are not production tested and are for informational purposes only.

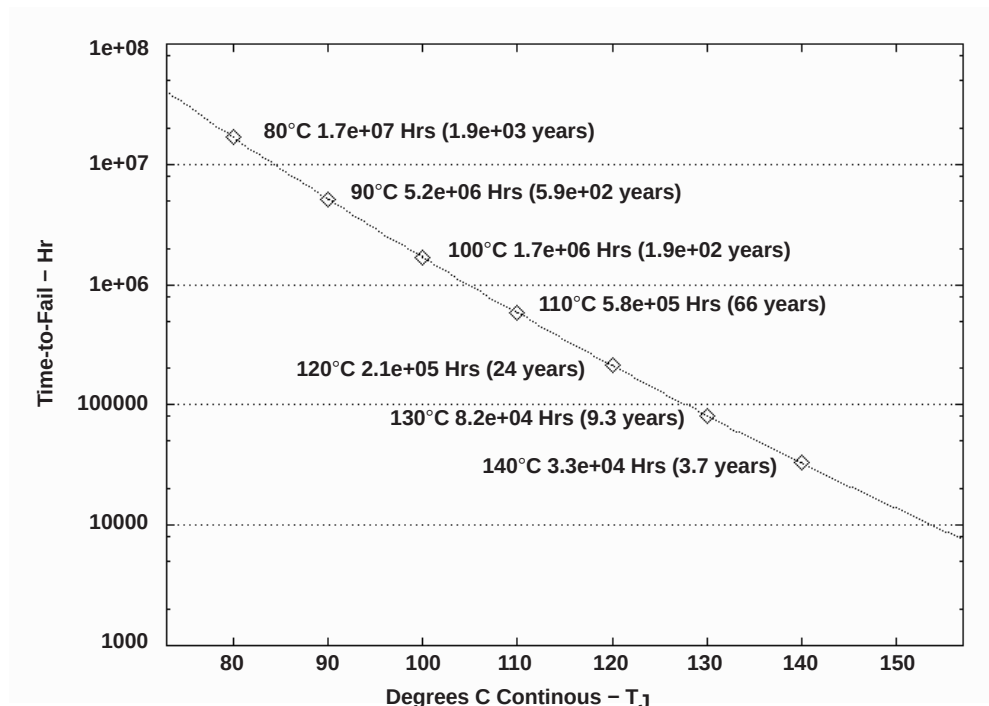


Figure 1. Wirebond Life Estimation Plot



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recommended operating conditions

		MIN	MAX	UNIT
Supply voltage, V_{DD}	Single supply	2.7	6	V
	Split supply	± 1.35	± 3	
Common-mode input voltage range, V_{ICR}		-0.2	$V_{DD}+0.2$	V
Shutdown on/off voltage level [‡]	V_{IH}	2		V
	V_{IL}		0.7	
Operating free-air temperature, T_A		-40	125	°C

[‡] Relative to voltage on the GND terminal of the device.



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electrical characteristics at specified free-air temperature, $V_{DD} = 3\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A [†]	MIN	TYP	MAX	UNIT
V _{IO}	Input offset voltage	V _{DD} = 3 V, V _O = 1.5 V,	V _{IC} = 1.5 V, R _S = 50 Ω	25°C		150	1500	μV
				Full range			1700	
α _{VIO}	Temperature coefficient of input offset voltage					2		μV/°C
I _{IO}	Input offset current	V _{DD} = 3 V, V _O = 1.5 V,	V _{IC} = 1.5 V, R _S = 50 Ω	25°C		2.8	7	nA
				Full range			75	
I _{IB}	Input bias current	V _{DD} = 3 V, V _O = 1.5 V,	V _{IC} = 1.5 V, R _S = 50 Ω	25°C		4.4	14	nA
				Full range			75	
V _{OH}	High-level output voltage	I _{OH} = −2.5 mA		25°C		2.9		V
				Full range		2.8		
		I _{OH} = −10 mA		25°C		2.7		
				Full range		2.5		
V _{OL}	Low-level output voltage	V _{IC} = 1.5 V, I _{OL} = 2.5 mA		25°C		0.1		V
				Full range		0.2		
		V _{IC} = 1.5 V, I _{OL} = 10 mA		25°C		0.3		
				Full range		0.5		
I _{OS}	Short-circuit output current	Sourcing		25°C		50		mA
				Full range		20		
		Sinking		25°C		40		
				Full range		20		
I _O	Output current	Measured 1 V from rail		25°C		±40		mA
A _{VD}	Large-signal differential voltage amplification	R _L = 10 kΩ		25°C		90	105	dB
				Full range		89		
r _{i(d)}	Differential input resistance			25°C		10 ⁹		Ω
c _{i(c)}	Common-mode input capacitance	f = 10 kHz		25°C		7		pF
z _o	Closed-loop output impedance	f = 100 kHz,	A _V = 10	25°C		33		Ω
CMRR	Common-mode rejection ratio	V _{ICR} = 0 V to 3 V, R _S = 50 Ω		25°C		66	80	dB
				Full range		60		
k _{SVR}	Supply voltage rejection ratio (ΔV _{DD} /ΔV _{IO})	V _{DD} = 2.7 V to 6 V, No load	V _{IC} = V _{DD} /2,	25°C		80	85	dB
				Full range		75		
		V _{DD} = 3 V to 5 V, No load	V _{IC} = V _{DD} /2,	25°C		85	95	
				Full range		80		
I _{DD}	Supply current (per channels)	V _O = 1.5 V,	No load	25°C		0.5	0.575	mA
				Full range		0.9		
I _{DD} (SHDN)	Supply current in shutdown (TLV2460, TLV2463)	SHDN < 0.7 V, Per channel in shutdown		25°C		0.3		μA
				Full range		2.5		

† Full range is -40°C to 125°C for the Q suffix and -55°C to 125°C for the M suffix.



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operating characteristics at specified free-air temperature, $V_{DD} = 3\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A [†]	MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain	V _{O(PP)} = 2 V, R _L = 10 kΩ		C _L = 160 pF, 25°C	1	1.6		V/μs
				Full range	0.8			
V _n	Equivalent input noise voltage	f = 100 Hz		25°C		16		nV/√Hz
		f = 1 kHz		25°C		11		
I _n	Equivalent input noise current	f = 1 kHz		25°C		0.13		pA/√Hz
THD + N	Total harmonic distortion plus noise	V _{O(PP)} = 2 V, R _L = 10 kΩ, f = 1 kHz	A _V = 1	25°C		0.006%		
			A _V = 10			0.02%		
			A _V = 100			0.08%		
t _(on)	Amplifier turnon time	A _V = 1, R _L = 10 kΩ	Both channels	25°C		7.6		μs
			Channel 1 only, Channel 2 on			7.65		
t _(off)	Amplifier turnoff time	A _V = 1, R _L = 10 kΩ	Both channels	25°C		333		ns
			Channel 1 only, Channel 2 on			328		
			Channel 2 only, Channel 1 on			329		
Gain-bandwidth product		f = 10 kHz, C _L = 160 pF	R _L = 10 kΩ,	25°C		5.2		MHz
t _s	Settling time	V(STEP) _{PP} = 2 V, A _V = -1, C _L = 10 pF, R _L = 10 kΩ	0.1%	25°C		1.47		μs
			0.01%			1.78		
		V(STEP) _{PP} = 2 V, A _V = -1, C _L = 56 pF, R _L = 10 kΩ	0.1%			1.77		
			0.01%			1.98		
φ _m	Phase margin at unity gain	R _L = 10 kΩ, C _L = 160 pF		25°C		44°		
Gain margin				25°C		7		dB

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electrical characteristics at specified free-air temperature, $V_{DD} = 5\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A [†]	MIN	TYP	MAX	UNIT
V _{IO}	Input offset voltage	V _{DD} = 5 V, V _O = 2.5 V,	V _{IC} = 2.5, R _S = 50 Ω	25°C		150	1500	μV
				Full range			1700	
α _{VIO}	Temperature coefficient of input offset voltage			25°C		2		μV/°C
I _{IO}	Input offset current	V _{DD} = 5 V, V _O = 2.5 V,	V _{IC} = 2.5 V, R _S = 50 Ω	25°C		0.3	7	nA
				Full range			60	
I _{IB}	Input bias current	V _{DD} = 5 V, V _O = 2.5 V,	V _{IC} = 2.5 V, R _S = 50 Ω	25°C		1.3	14	nA
				Full range			60	
V _{OH}	High-level output voltage	I _{OH} = −2.5 mA		25°C		4.9		V
				Full range		4.8		
		I _{OH} = −10 mA		25°C		4.8		
				Full range		4.7		
V _{OL}	Low-level output voltage	V _{IC} = 2.5 V, I _{OL} = 2.5 mA		25°C		0.1		V
				Full range		0.2		
		V _{IC} = 2.5 V, I _{OL} = 10 mA		25°C		0.2		
				Full range		0.3		
I _{OS}	Short-circuit output current	Sourcing		25°C		145		mA
				Full range		60		
		Sinking		25°C		100		
				Full range		60		
I _O	Output current	Measured at 1 V from rail		25°C		±80		mA
A _{VD}	Large-signal differential voltage amplification	V _{IC} = 2.5 V, V _O = 1 V to 4 V	R _L = 10 kΩ,	25°C		92	109	dB
				Full range		90		
r _{i(d)}	Differential input resistance			25°C		10 ⁹		Ω
c _{i(c)}	Common-mode input capacitance	f = 10 kHz		25°C		7		pF
z _o	Closed-loop output impedance	f = 100 kHz, A _V = 10		25°C		29		Ω
CMRR	Common-mode rejection ratio	V _{ICR} = 0 V to 5 V, R _S = 50 Ω		25°C		71	85	dB
				Full range		60		
k _{SVR}	Supply voltage rejection ratio (ΔV _{DD} /ΔV _{IO})	V _{DD} = 2.7 V to 6 V, V _{IC} = V _{DD} /2, No load		25°C		80	85	dB
				Full range		75		
		V _{DD} = 3 V to 5 V, V _{IC} = V _{DD} /2, No load		25°C		85	95	dB
				Full range		80		
I _{DD}	Supply current (per channel)	V _O = 2.5 V, No load,		25°C		0.55	0.65	mA
				Full range		1		
I _{DD} (SHDN)	Supply current in shutdown (TLV2460, TLV2463)	SHDN < 0.7 V, Per channels in shutdown		25°C		1		μA
				Full range		3		

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operating characteristics at specified free-air temperature, $V_{DD} = 5\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A [†]	MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain	V _{O(PP)} = 2 V, R _L = 10 kΩ		C _L = 160 pF, Full range	25°C	1	1.6	V/μs
					0.8			
V _n	Equivalent input noise voltage	f = 100 Hz		25°C		14	nV/√Hz	
		f = 1 kHz		25°C		11		
I _n	Equivalent input noise current	f = 100 Hz		25°C		0.13	pA/√Hz	
THD + N	Total harmonic distortion plus noise	V _{O(PP)} = 4 V, R _L = 10 kΩ, f = 10 kHz	A _V = 1	25°C		0.004%		
			A _V = 10			0.01%		
			A _V = 100			0.04%		
t _(on)	Amplifier turnon time	A _V = 1, R _L = 10 kΩ	Both channels	25°C		7.6	μs	
			Channel 1 only, Channel 2 on			7.65		
			Channel 2 only, Channel 1 on			7.25		
t _(off)	Amplifier turnoff time	A _V = 1, R _L = 10 kΩ	Both channels	25°C		333	ns	
			Channel 1 only, Channel 2 on			328		
			Channel 2 only, Channel 1 on			329		
Gain-bandwidth product		f = 10 kHz, C _L = 160 pF	R _L = 10 kΩ,	25°C		6.4	MHz	
t _s	Settling time	V(STEP)PP = 2 V, A _V = -1, C _L = 10 pF, R _L = 10 kΩ	0.1%	25°C		1.53	μs	
			0.01%			1.83		
		V(STEP)PP = 2 V, A _V = -1, C _L = 56 pF, R _L = 10 kΩ	0.1%			3.13		
			0.01%			3.33		
φ _m	Phase margin at unity gain	R _L = 10 kΩ, C _L = 160 pF		25°C		45°		
	Gain margin			25°C		7	dB	

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TYPICAL CHARACTERISTICS

Table of Graphs

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I_{IB}	Input bias current	vs Free-air temperature	3, 4
I_{IO}	Input offset current	vs Free-air temperature	3, 4
V_{OH}	High-level output voltage	vs High-level output current	5, 6
V_{OL}	Low-level output voltage	vs Low-level output current	7, 8
$V_{O(PP)}$	Peak-to-peak output voltage	vs Frequency	9, 10
	Open-loop gain	vs Frequency	11, 12
	Phase	vs Frequency	11, 12
A_{VD}	Differential voltage amplification	vs Load resistance	13
	Capacitive load	vs Load resistance	14
Z_o	Output impedance	vs Frequency	15, 16
CMRR	Common-mode rejection ratio	vs Frequency	17
k_{SVR}	Supply-voltage rejection ratio	vs Frequency	18, 19
I_{DD}	Supply current	vs Supply voltage	20
		vs Free-air temperature	21
	Amplifier turnon characteristics		22
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	Supply current turnon		24
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	Shutdown supply current	vs Free-air temperature	26
SR	Slew rate	vs Supply voltage	27
V_n	Equivalent input noise voltage	vs Frequency	28, 29
		vs Common-mode input voltage	30, 31
THD	Total harmonic distortion	vs Frequency	32, 33
THD+N	Total harmonic distortion plus noise	vs Peak-to-peak signal amplitude	34, 35
ϕ_m	Phase margin	vs Frequency	11, 12
		vs Load capacitance	36
		vs Free-air temperature	37
	Gain bandwidth product	vs Supply voltage	38
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TYPICAL CHARACTERISTICS

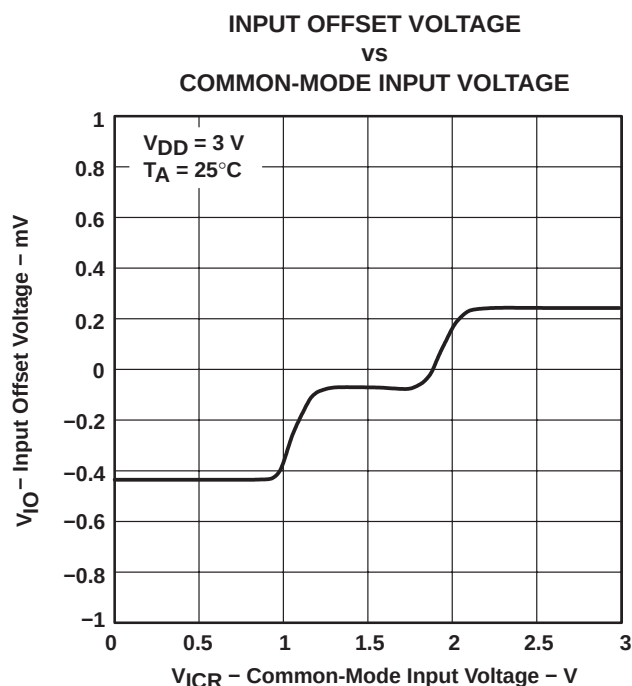


Figure 2

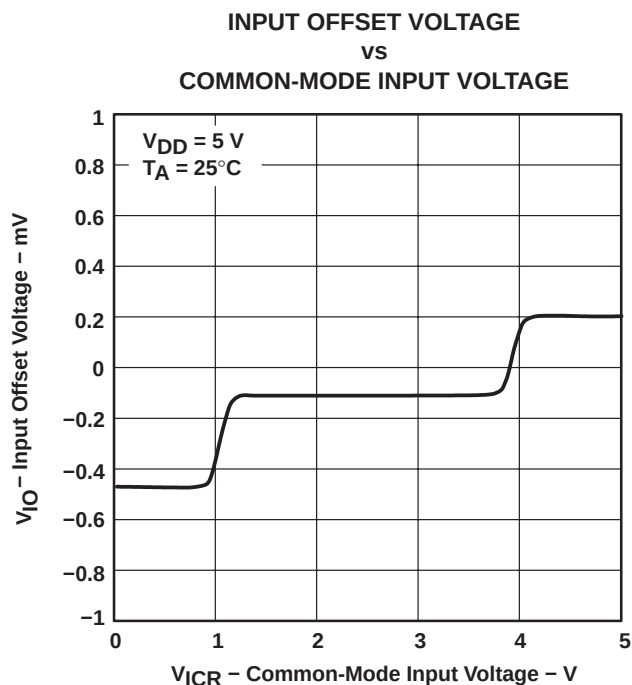


Figure 3

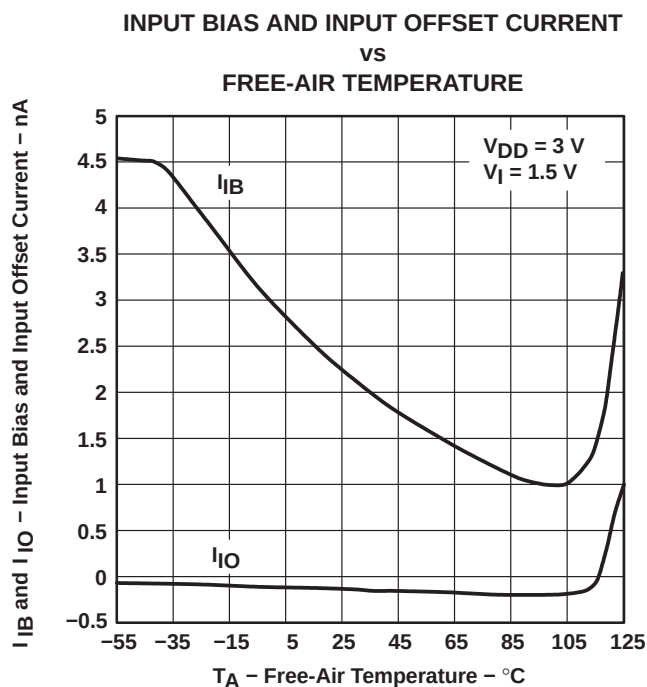


Figure 4

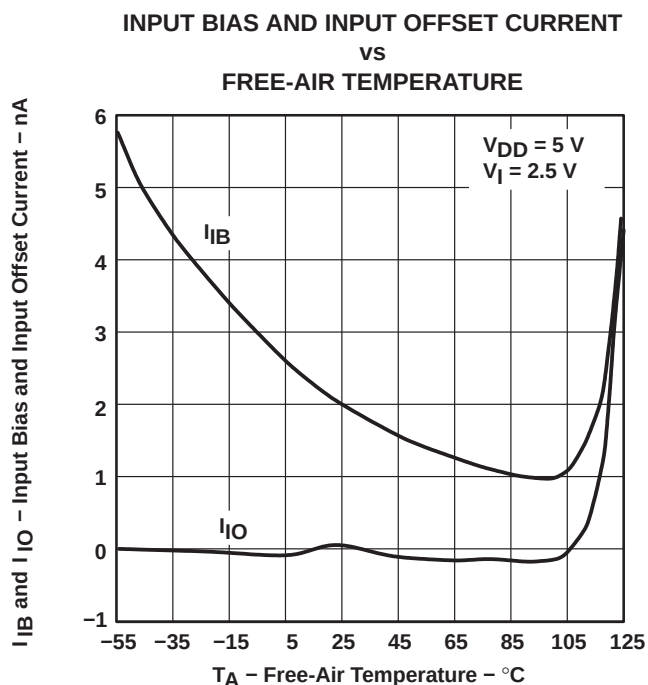
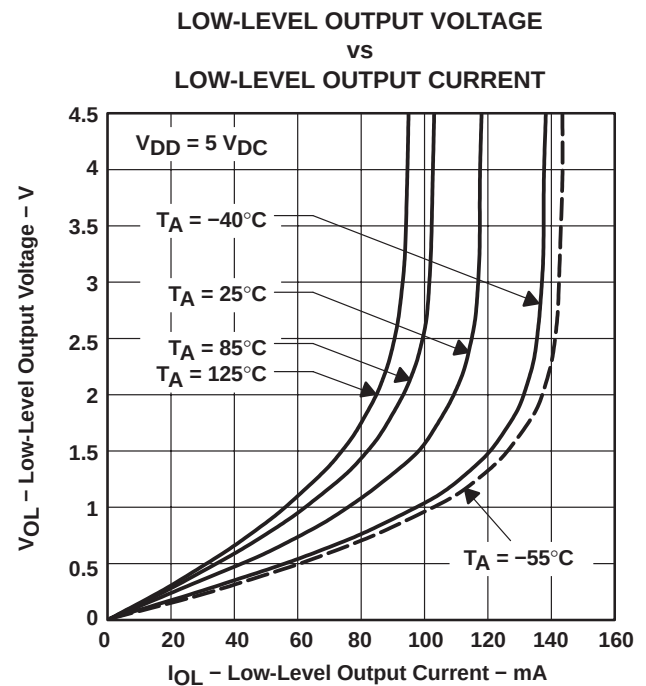
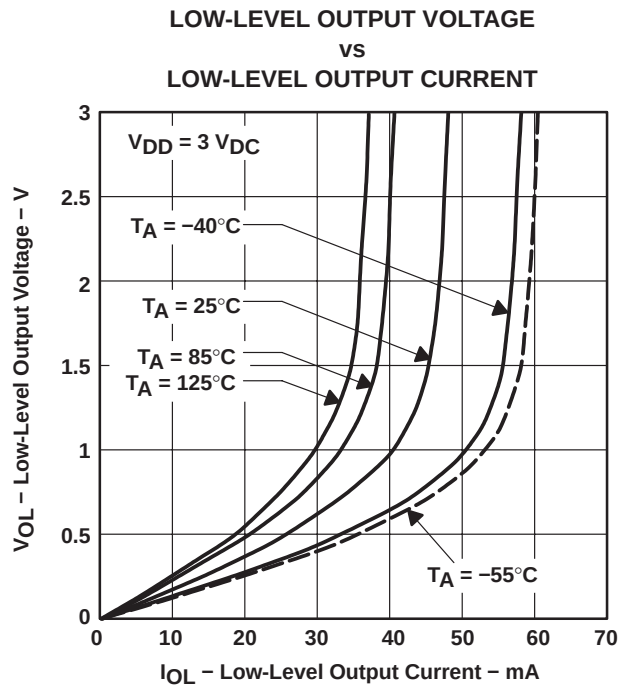
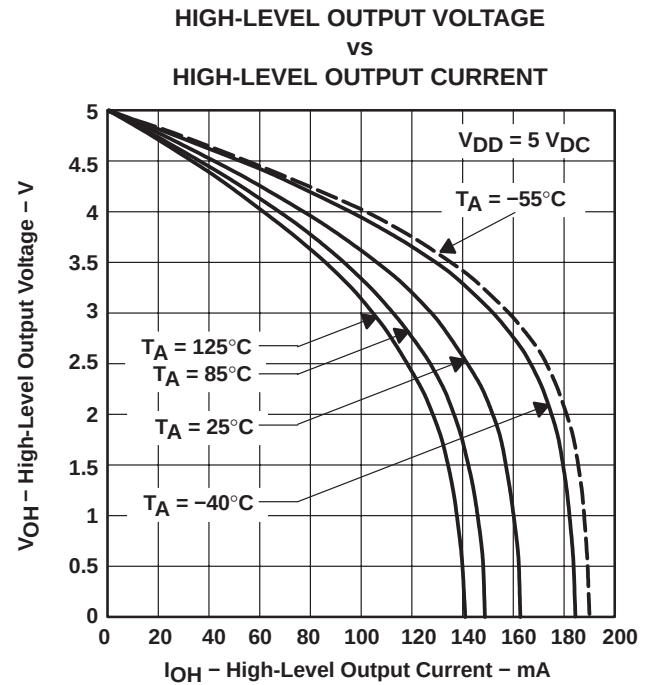
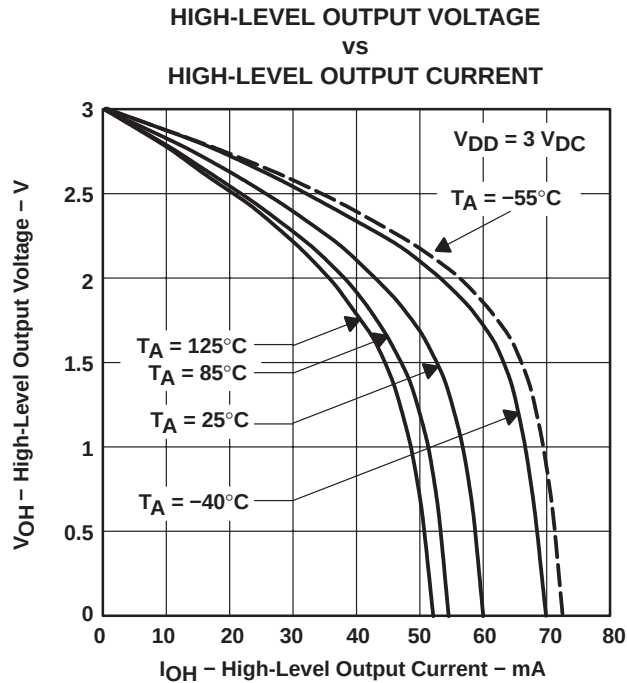


Figure 5

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP
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TYPICAL CHARACTERISTICS

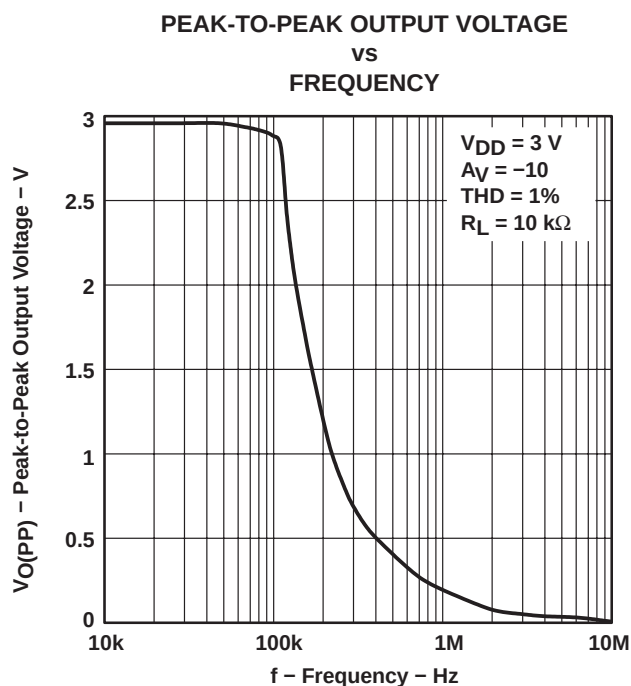


Figure 10

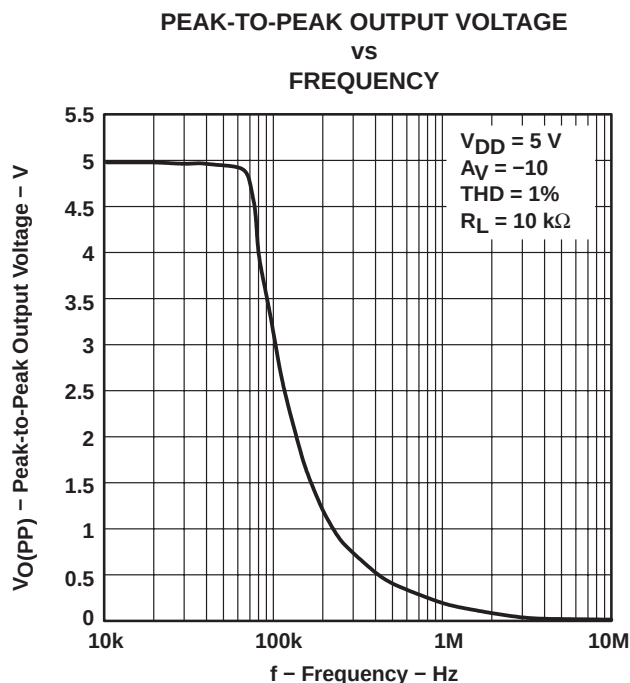


Figure 11

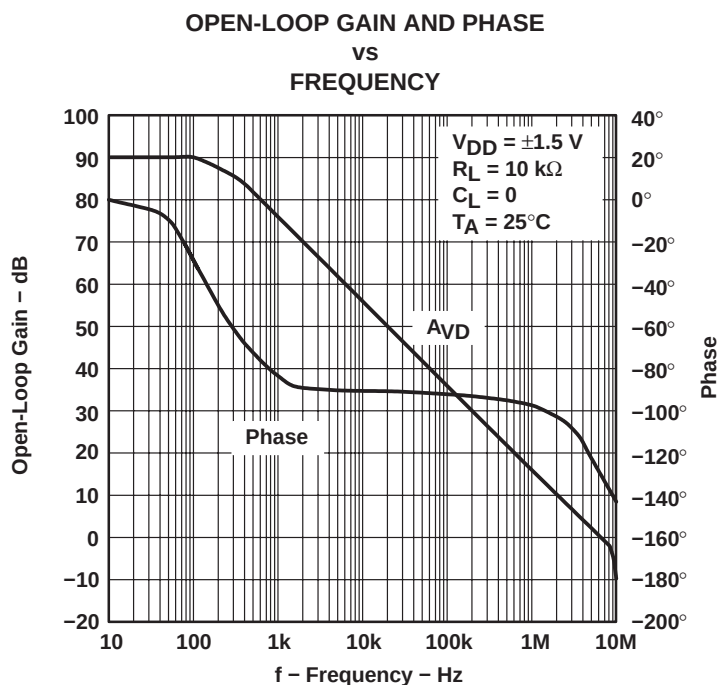


Figure 12

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP
FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT
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TYPICAL CHARACTERISTICS

**OPEN-LOOP GAIN AND PHASE
VS
FREQUENCY**

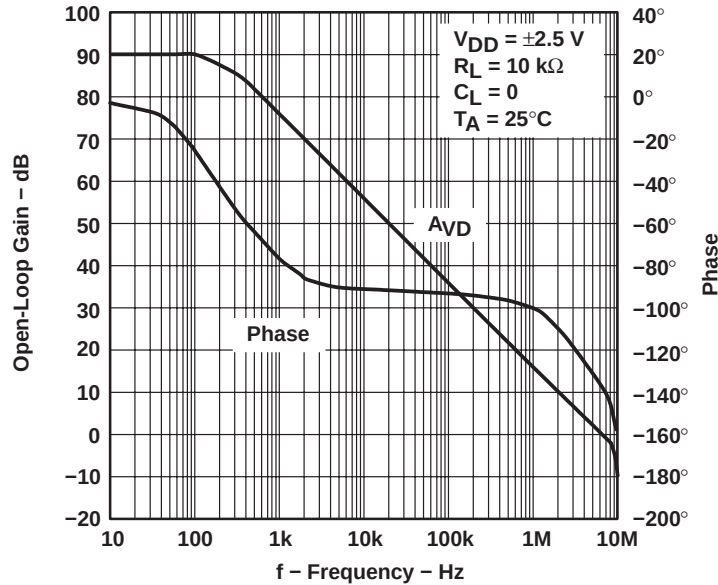


Figure 13

**DIFFERENTIAL VOLTAGE AMPLIFICATION
VS
LOAD RESISTANCE**

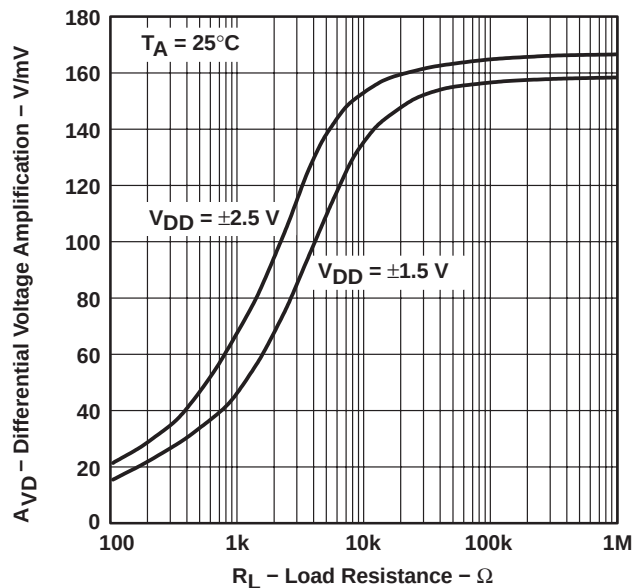


Figure 14

**CAPACITIVE LOAD
VS
LOAD RESISTANCE**

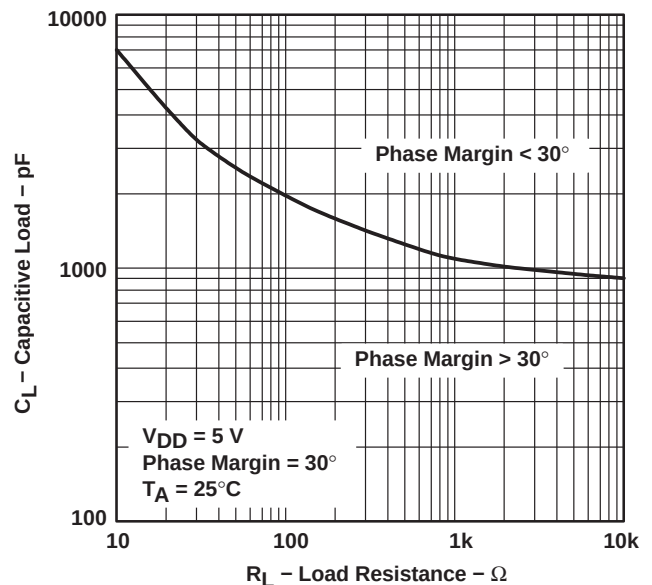


Figure 15

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP

FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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TYPICAL CHARACTERISTICS

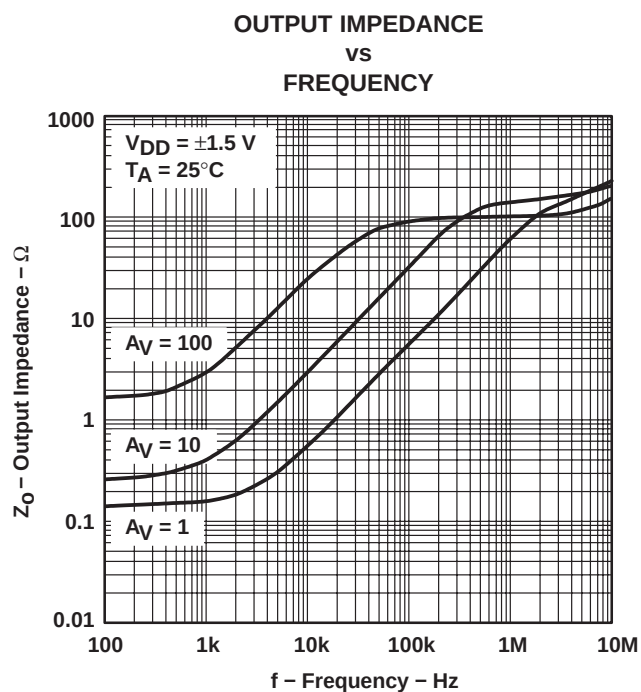


Figure 16

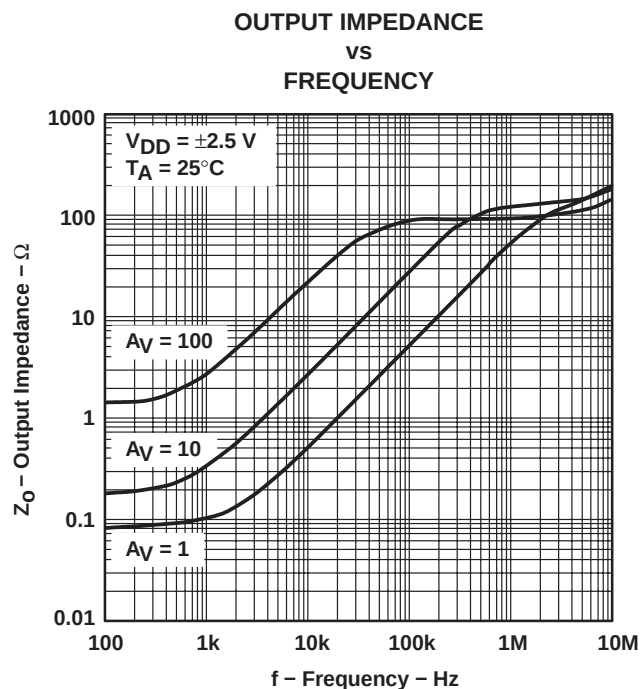


Figure 17

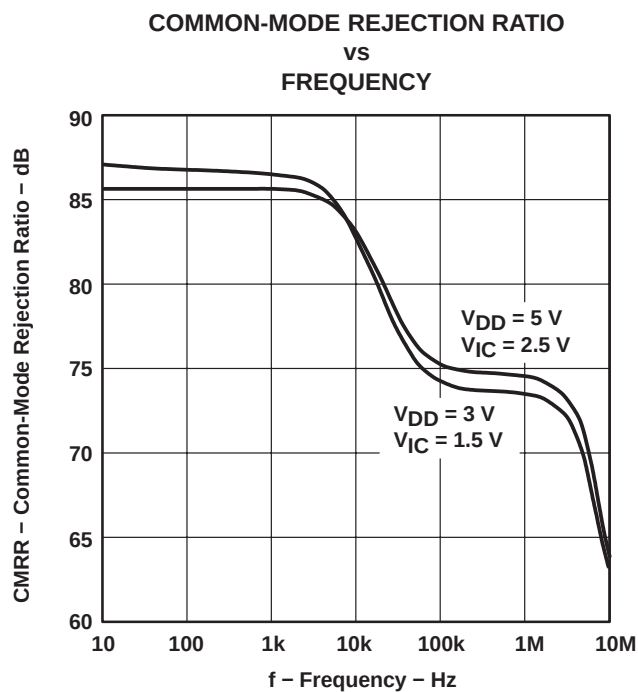


Figure 18

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP
FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT
OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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TYPICAL CHARACTERISTICS

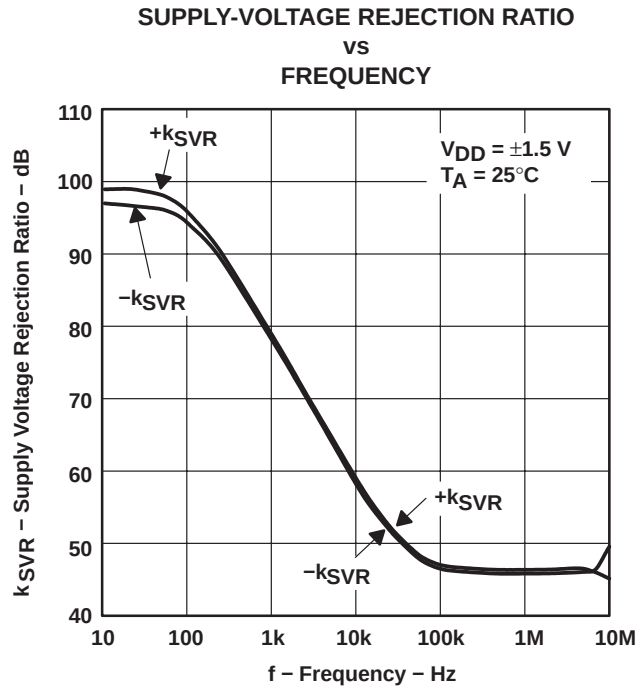


Figure 19

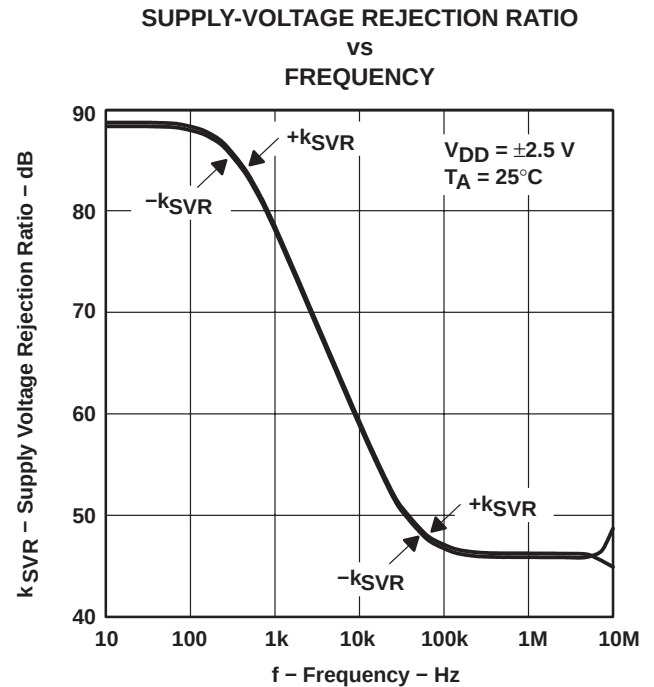


Figure 20

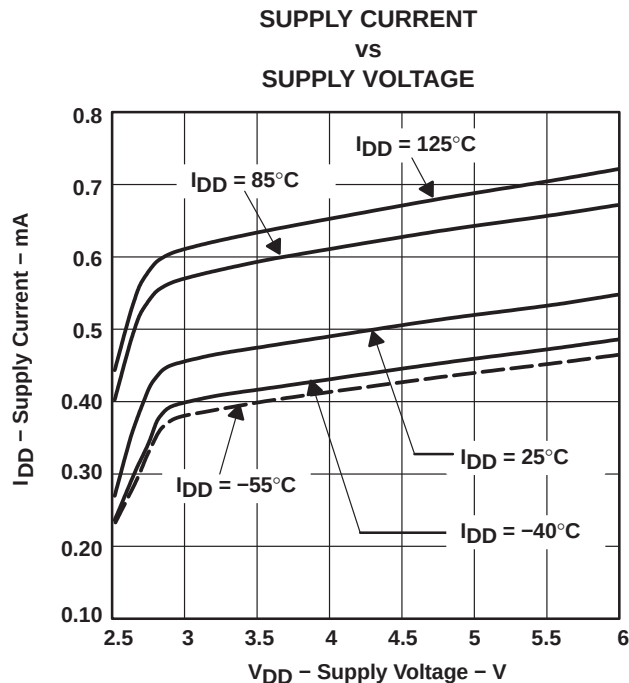


Figure 21

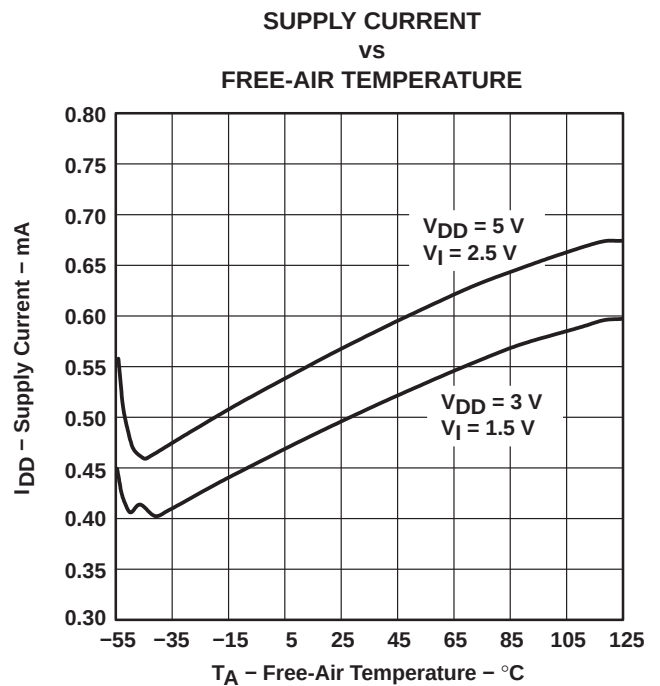


Figure 22

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP

FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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TYPICAL CHARACTERISTICS

AMPLIFIER WITH A SHUTDOWN PULSE
TURNON CHARACTERISTICS

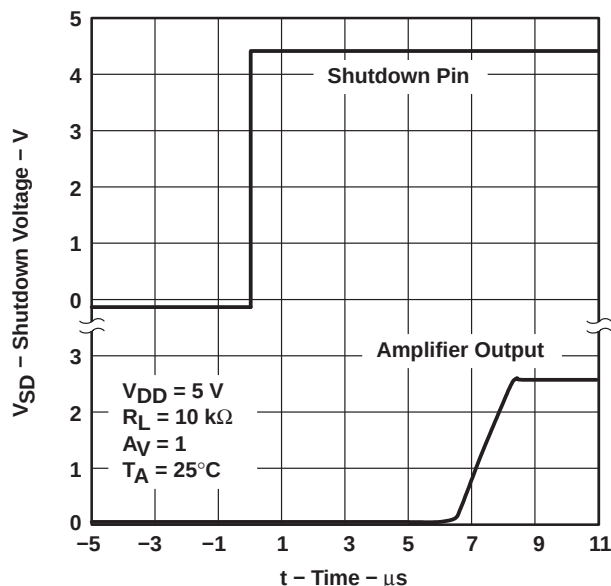


Figure 23

AMPLIFIER WITH A SHUTDOWN PULSE
TURNOFF CHARACTERISTICS

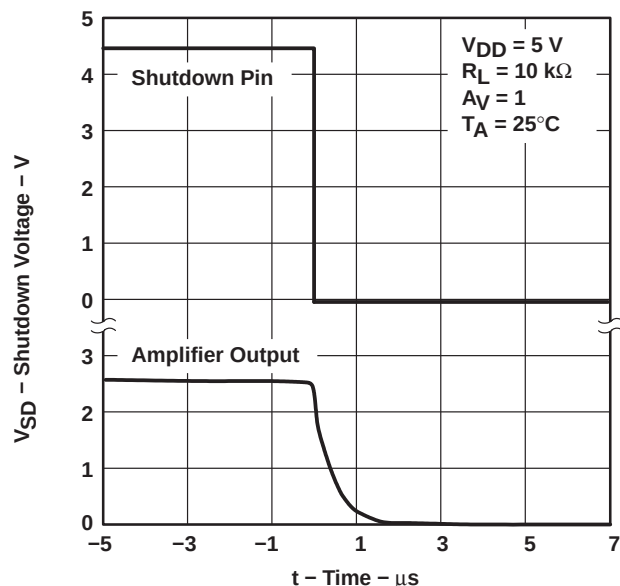


Figure 24

SUPPLY CURRENT WITH A SHUTDOWN PULSE
TURNON CHARACTERISTICS

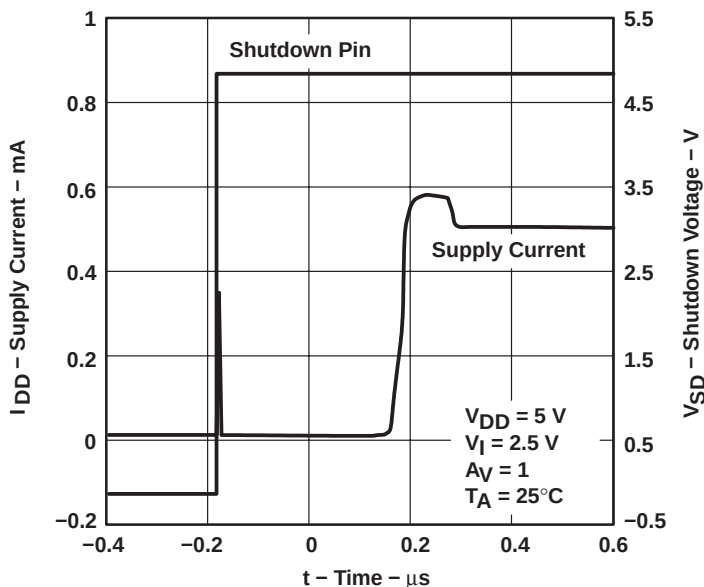


Figure 25

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP
FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT
OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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TYPICAL CHARACTERISTICS

TURN-OFF SUPPLY CURRENT
WITH A SHUTDOWN PULSE

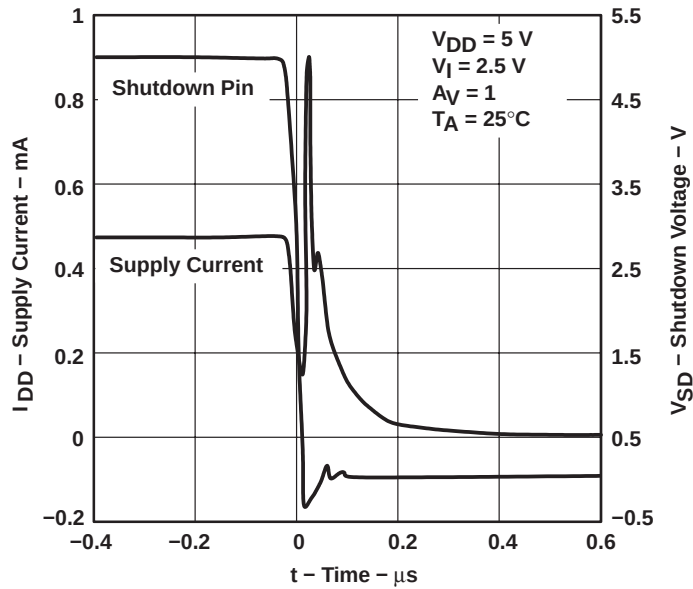


Figure 26

SHUTDOWN SUPPLY CURRENT
VS
FREE-AIR TEMPERATURE

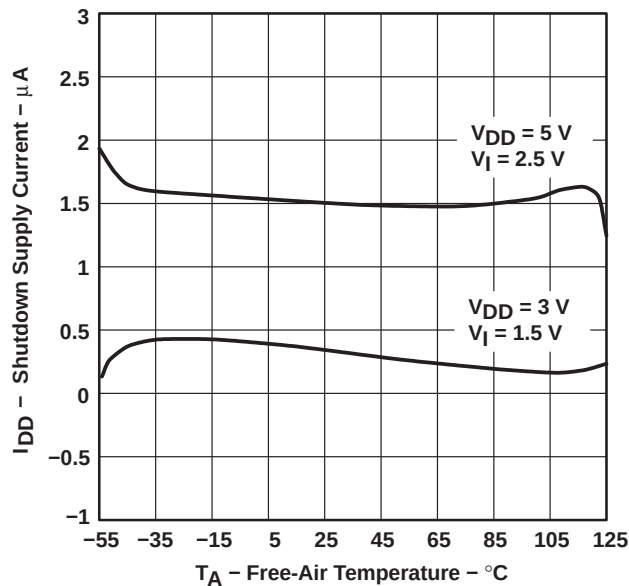


Figure 27

SLEW RATE
VS
SUPPLY VOLTAGE

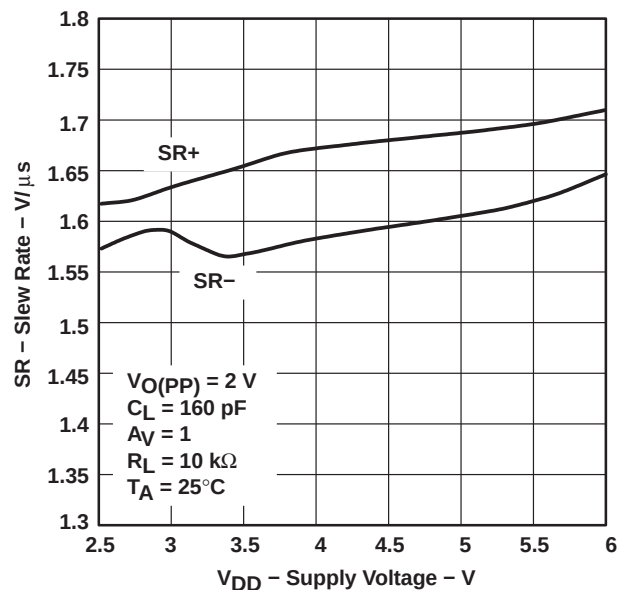


Figure 28

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP

FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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TYPICAL CHARACTERISTICS

EQUIVALENT INPUT NOISE VOLTAGE
VS
FREQUENCY

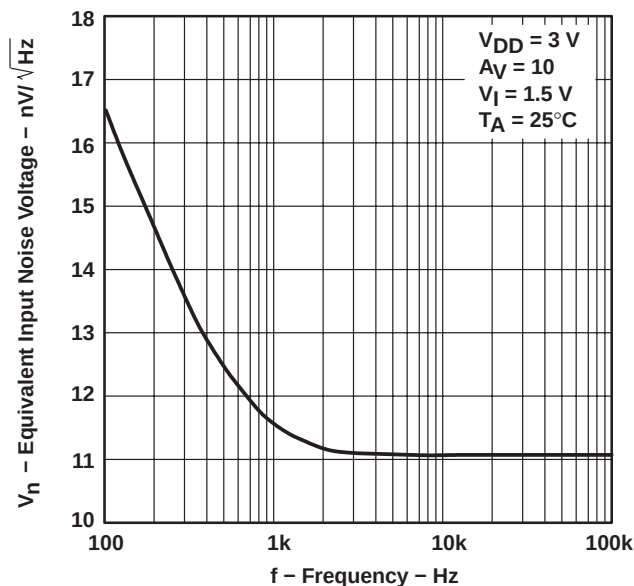


Figure 29

EQUIVALENT INPUT NOISE VOLTAGE
VS
FREQUENCY

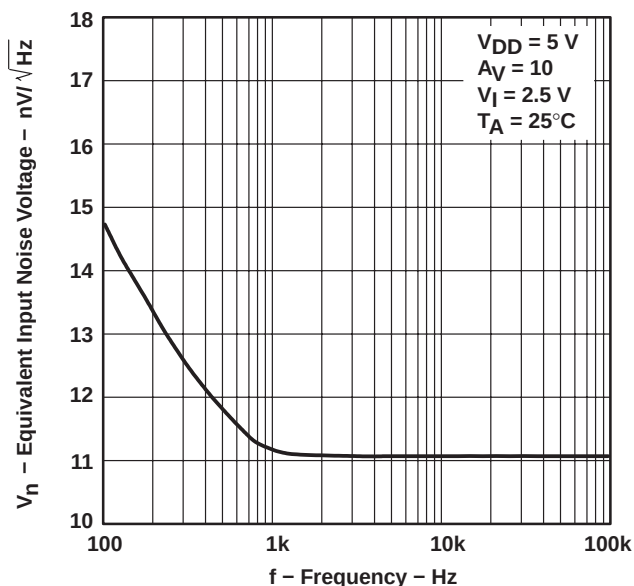


Figure 30

EQUIVALENT INPUT NOISE VOLTAGE
VS
COMMON-MODE INPUT VOLTAGE

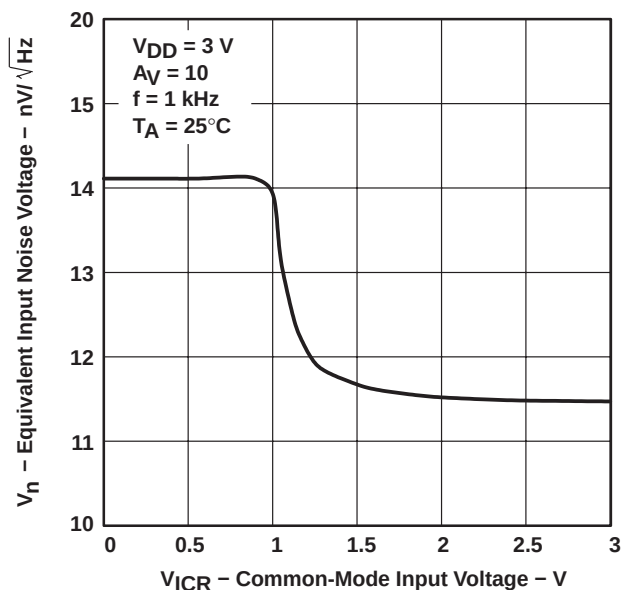


Figure 31

EQUIVALENT INPUT NOISE VOLTAGE
VS
COMMON-MODE INPUT VOLTAGE

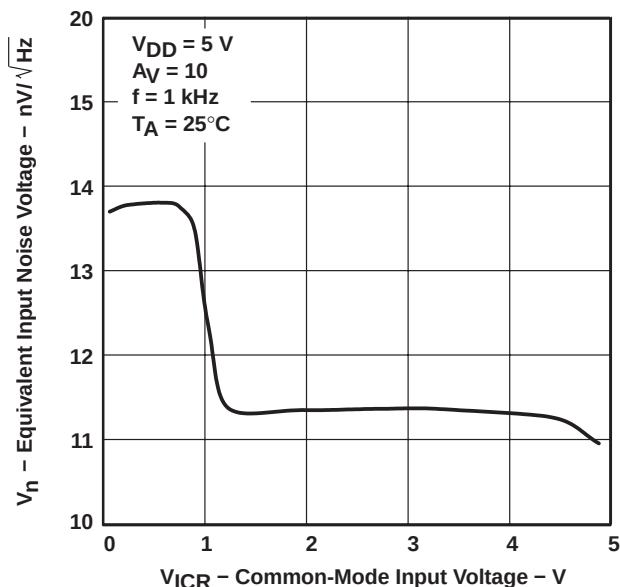


Figure 32

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP
FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT
OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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TYPICAL CHARACTERISTICS

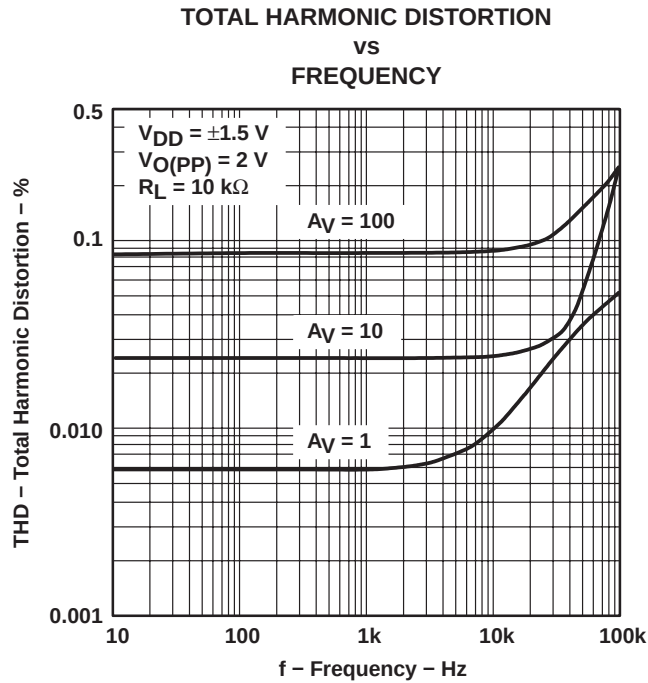


Figure 33

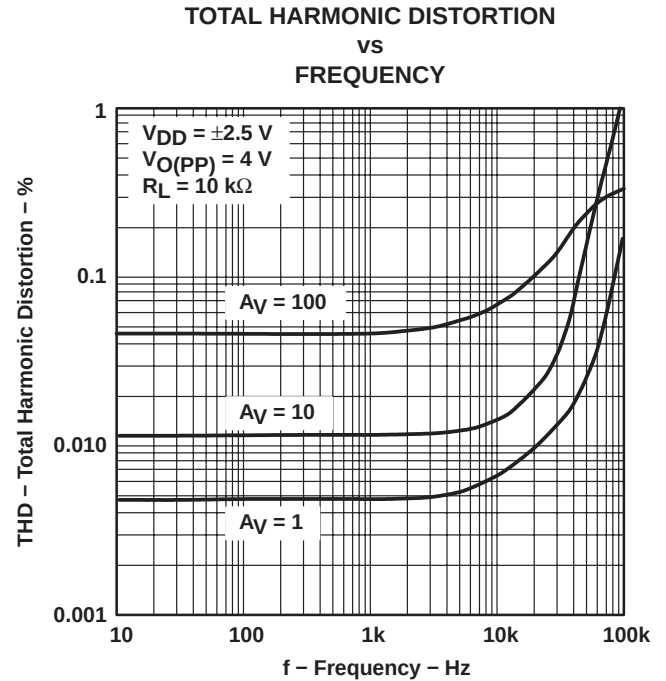


Figure 34

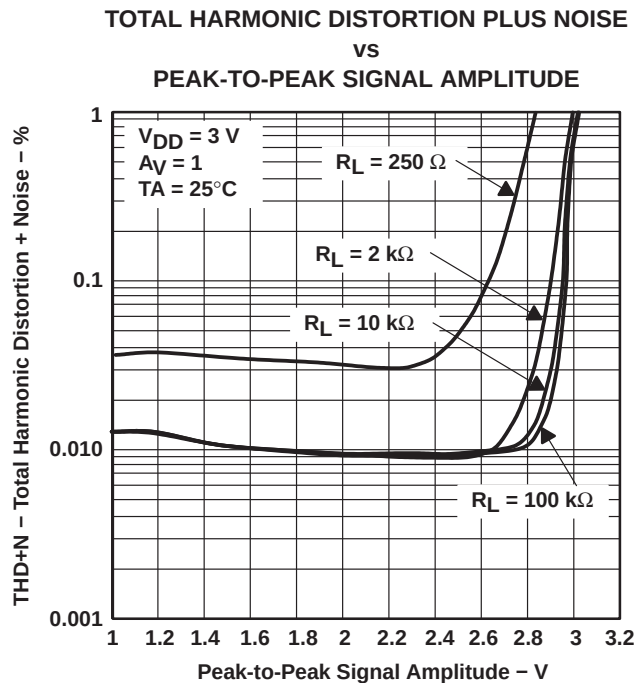


Figure 35

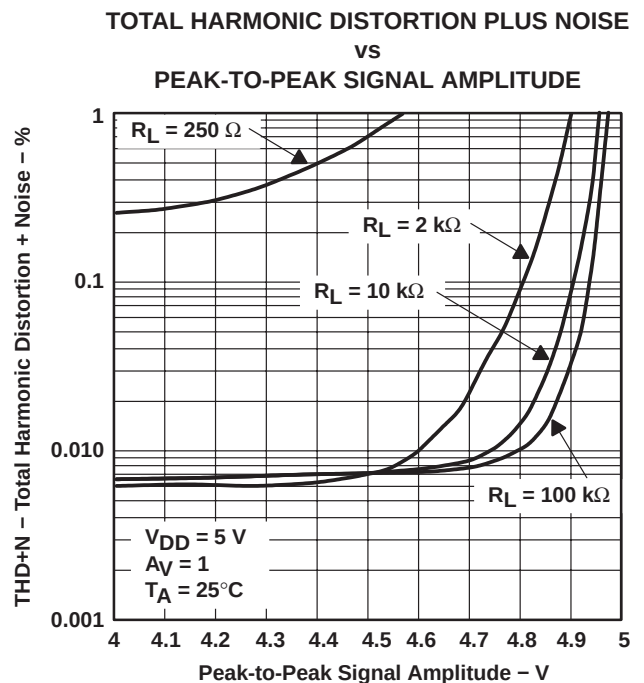


Figure 36

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP

FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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TYPICAL CHARACTERISTICS

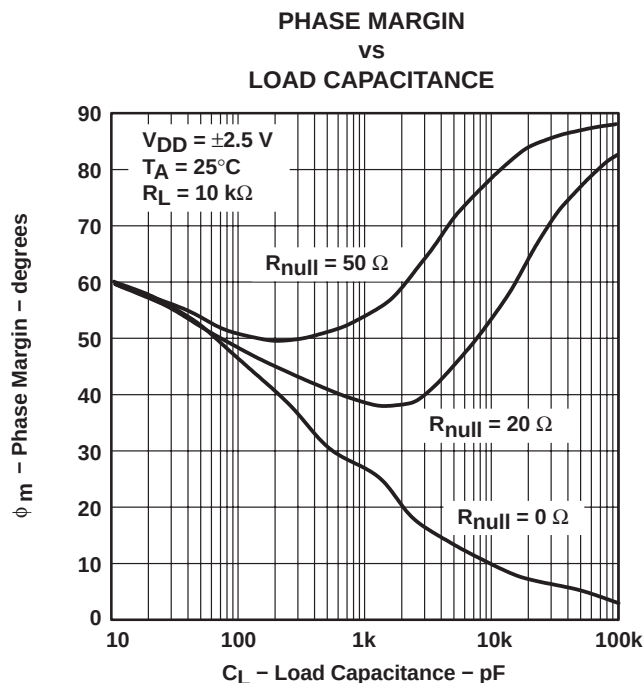


Figure 37

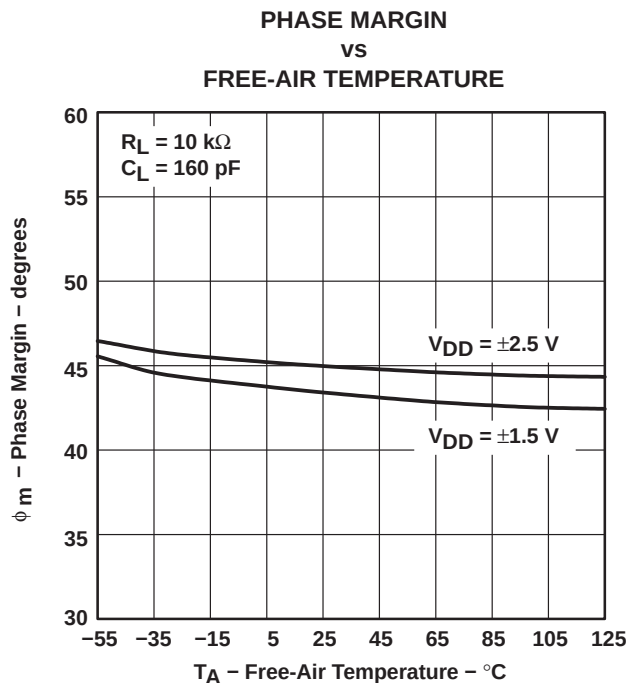


Figure 38

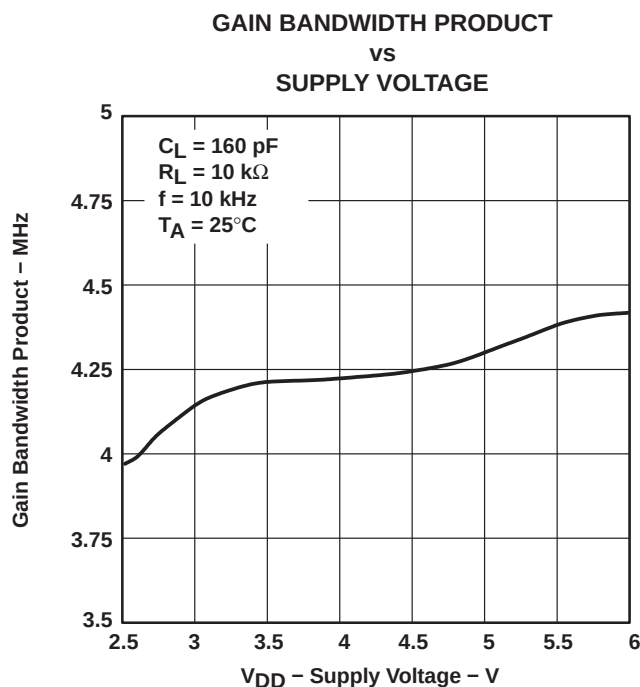


Figure 39

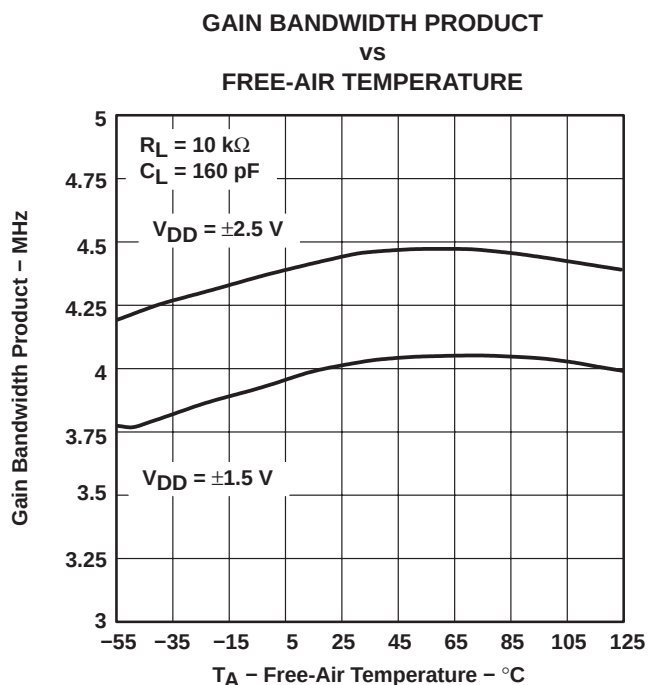


Figure 40

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP
FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT
OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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TYPICAL CHARACTERISTICS

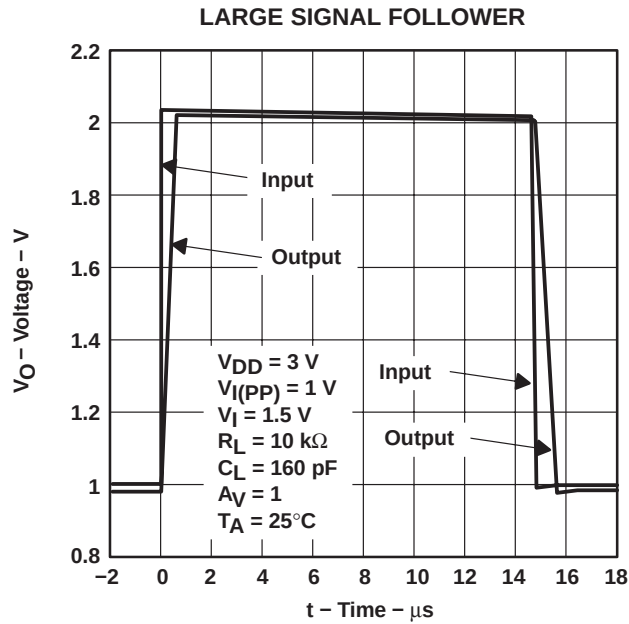


Figure 41

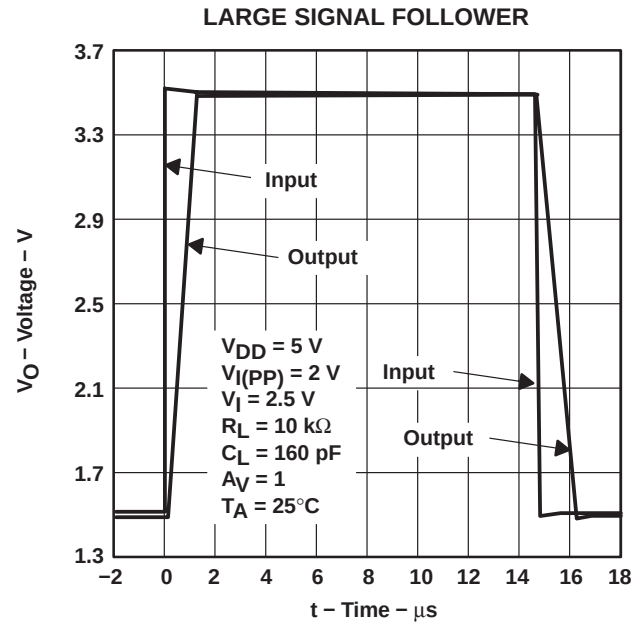


Figure 42

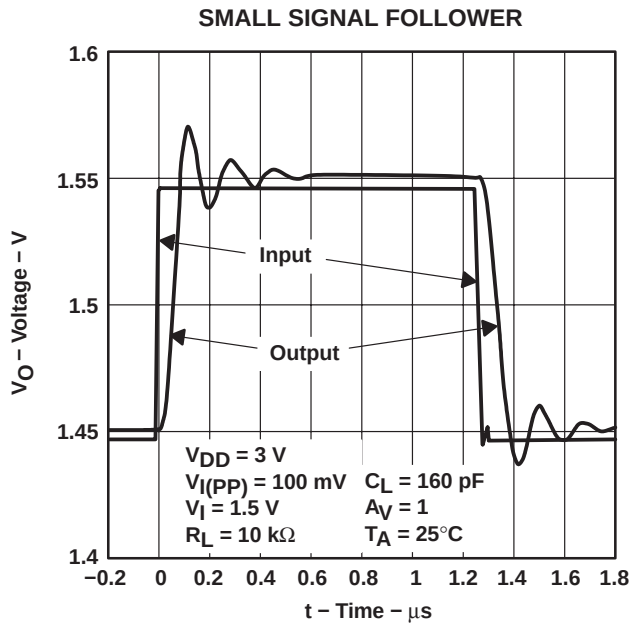


Figure 43

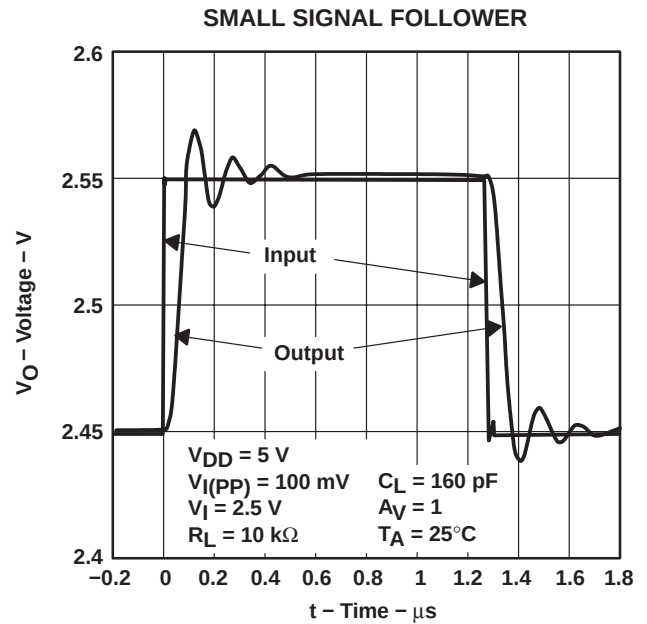


Figure 44

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP

FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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TYPICAL CHARACTERISTICS

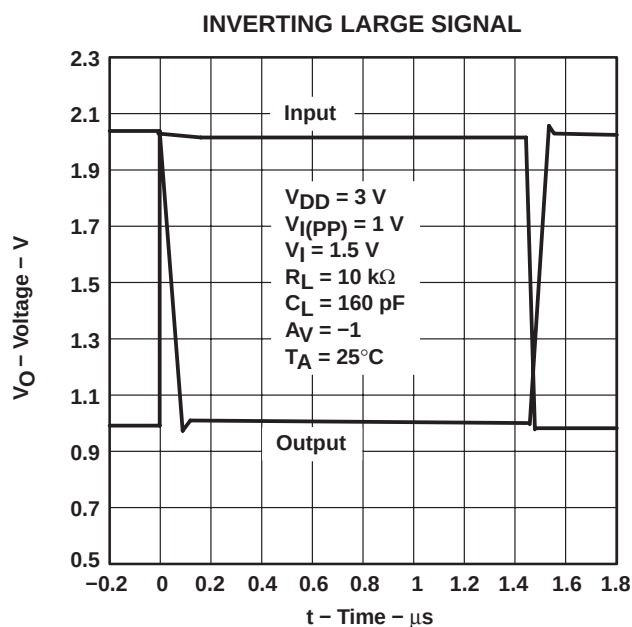


Figure 45

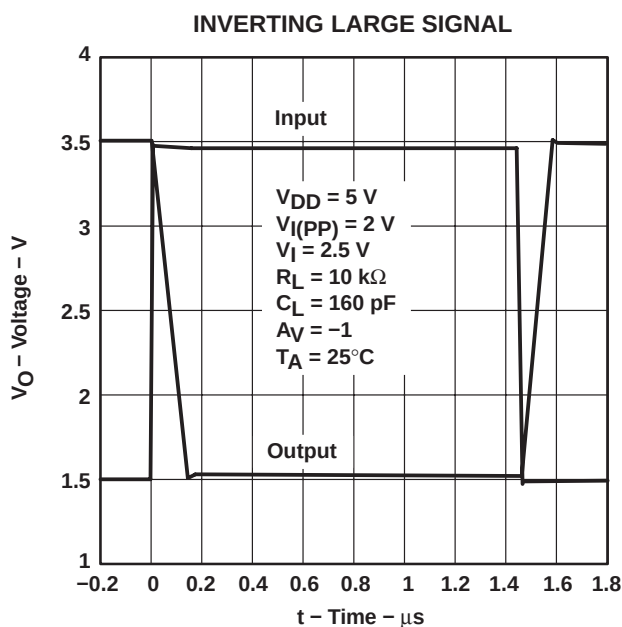


Figure 46

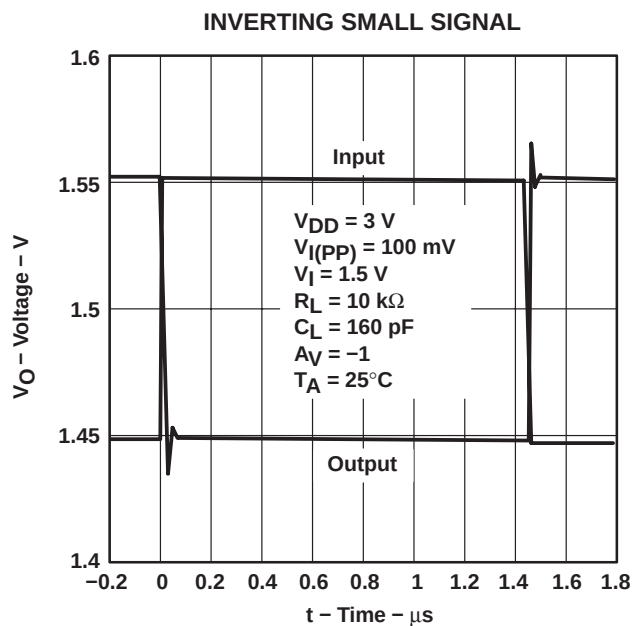


Figure 47

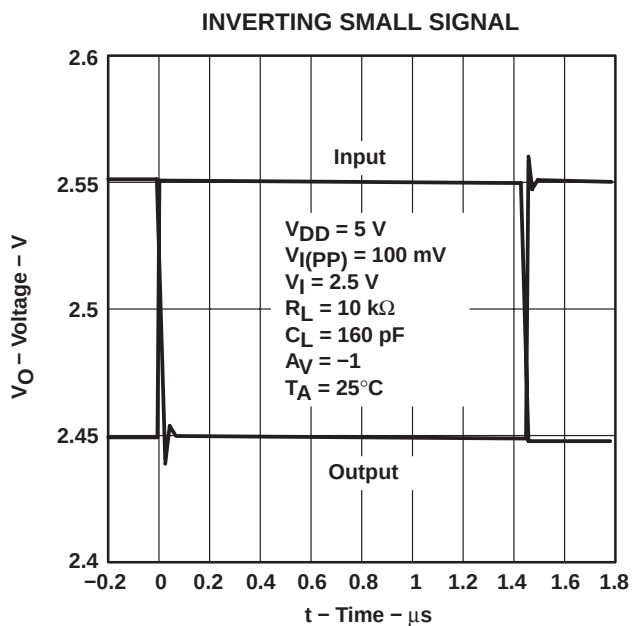


Figure 48

PARAMETER MEASUREMENT INFORMATION

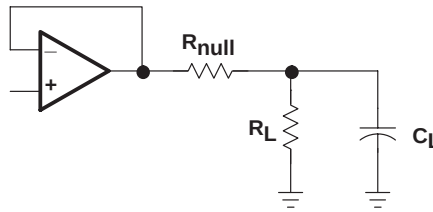


Figure 49

APPLICATION INFORMATION

driving a capacitive load

When the amplifier is configured in this manner, capacitive loading directly on the output will decrease the device's phase margin leading to high frequency ringing or oscillations. Therefore, for capacitive loads of greater than 10 pF, it is recommended that a resistor be placed in series (R_{NULL}) with the output of the amplifier, as shown in Figure 49. A minimum value of 20 Ω should work well for most applications.

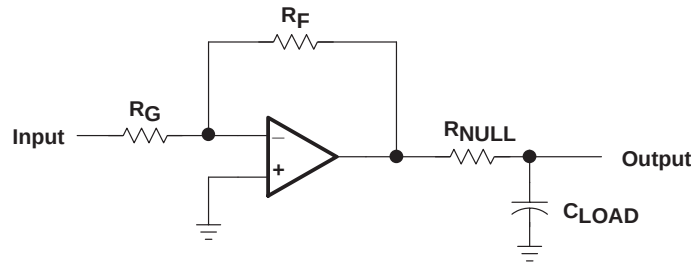


Figure 50. Driving a Capacitive Load

offset voltage

The output offset voltage, (V_{OO}) is the sum of the input offset voltage (V_{IO}) and both input bias currents (I_{IB}) times the corresponding gains. The following schematic and formula can be used to calculate the output offset voltage:

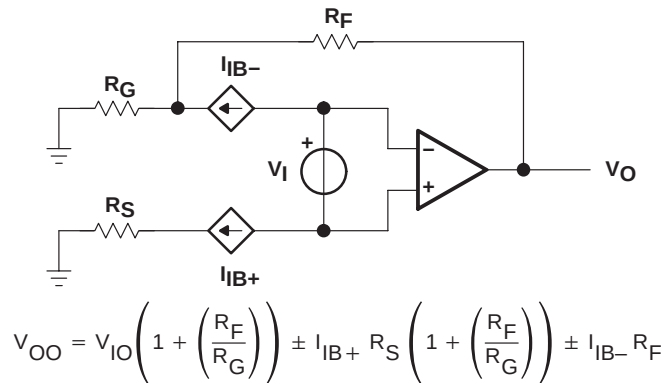


Figure 51. Output Offset Voltage Model

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP

FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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APPLICATION INFORMATION

general configurations

When receiving low-level signals, limiting the bandwidth of the incoming signals into the system is often required. The simplest way to accomplish this is to place an RC filter at the noninverting terminal of the amplifier (see Figure 51).

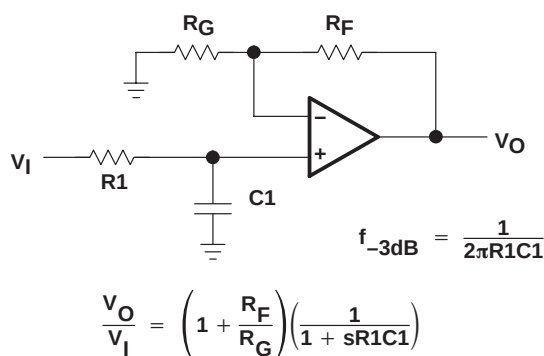


Figure 52. Single-Pole Low-Pass Filter

If even more attenuation is needed, a multiple pole filter is required. The Sallen-Key filter can be used for this task. For best results, the amplifier should have a bandwidth that is 8 to 10 times the filter frequency bandwidth. Failure to do this can result in phase shift of the amplifier.

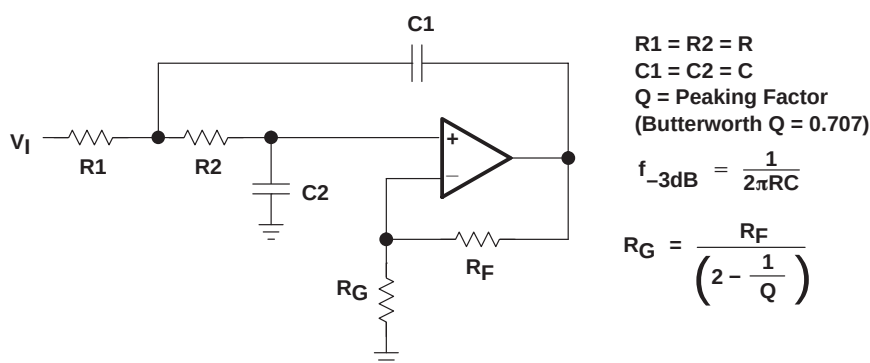


Figure 53. 2-Pole Low-Pass Sallen-Key Filter

APPLICATION INFORMATION

shutdown function

Two members of the TLV246x family (TLV2460/3) have a shutdown terminal for conserving battery life in portable applications. When the shutdown terminal is tied low, the supply current is reduced to 0.3 $\mu\text{A}/\text{channel}$, the amplifier is disabled, and the outputs are placed in a high impedance mode. To enable the amplifier, the shutdown terminal can either be left floating or pulled high. When the shutdown terminal is left floating, care should be taken to ensure that parasitic leakage current at the shutdown terminal does not inadvertently place the operational amplifier into shutdown. The shutdown terminal threshold is always referenced to $V_{DD}/2$. Therefore, when operating the device with split supply voltages (e.g. $\pm 2.5\text{ V}$), the shutdown terminal needs to be pulled to V_{DD-} (not GND) to disable the operational amplifier.

The amplifier's output with a shutdown pulse is shown in Figures 22, 23, 24, and 25. The amplifier is powered with a single 5-V supply and configured as a noninverting configuration with a gain of 5. The amplifier turnon and turnoff times are measured from the 50% point of the shutdown pulse to the 50% point of the output waveform. The times for the single, dual, and quad are listed in the data tables.

circuit layout considerations

To achieve the levels of high performance of the TLV246x, follow proper printed-circuit board design techniques. A general set of guidelines is given in the following.

- Ground planes – It is highly recommended that a ground plane be used on the board to provide all components with a low inductive ground connection. However, in the areas of the amplifier inputs and output, the ground plane can be removed to minimize the stray capacitance.
- Proper power supply decoupling – Use a 6.8- μF tantalum capacitor in parallel with a 0.1- μF ceramic capacitor on each supply terminal. It may be possible to share the tantalum among several amplifiers depending on the application, but a 0.1- μF ceramic capacitor should always be used on the supply terminal of every amplifier. In addition, the 0.1- μF capacitor should be placed as close as possible to the supply terminal. As this distance increases, the inductance in the connecting trace makes the capacitor less effective. The designer should strive for distances of less than 0.1 inches between the device power terminals and the ceramic capacitors.
- Sockets – Sockets can be used but are not recommended. The additional lead inductance in the socket pins will often lead to stability problems. Surface-mount packages soldered directly to the printed-circuit board is the best implementation.
- Short trace runs/compact part placements – Optimum high performance is achieved when stray series inductance has been minimized. To realize this, the circuit layout should be made as compact as possible, thereby minimizing the length of all trace runs. Particular attention should be paid to the inverting input of the amplifier. Its length should be kept as short as possible. This will help to minimize stray capacitance at the input of the amplifier.
- Surface-mount passive components – Using surface-mount passive components is recommended for high performance amplifier circuits for several reasons. First, because of the extremely low lead inductance of surface-mount components, the problem with stray series inductance is greatly reduced. Second, the small size of surface-mount components naturally leads to a more compact layout thereby minimizing both stray inductance and capacitance. If leaded components are used, it is recommended that the lead lengths be kept as short as possible.

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP

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APPLICATION INFORMATION

general power dissipation considerations

For a given θ_{JA} , the maximum power dissipation is shown in Figure 53 and is calculated by the following formula:

$$P_D = \left(\frac{T_{MAX} - T_A}{\theta_{JA}} \right)$$

Where:

P_D = Maximum power dissipation of THS246x IC (watts)

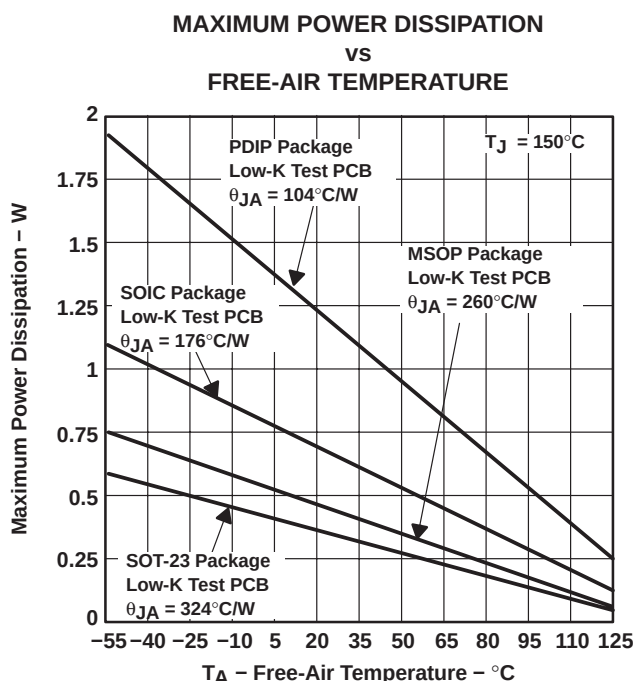
T_{MAX} = Absolute maximum junction temperature (150°C)

T_A = Free-ambient air temperature (°C)

$\theta_{JA} = \theta_{JC} + \theta_{CA}$

θ_{JC} = Thermal coefficient from junction to case

θ_{CA} = Thermal coefficient from case to ambient air (°C/W)



NOTE A: Results are with no air flow and using JEDEC Standard Low-K test PCB.

Figure 54. Maximum Power Dissipation vs Free-Air Temperature

TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP

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APPLICATION INFORMATION

macromodel information

Macromodel information provided was derived using Microsim *Parts*™ Release 8, the model generation software used with Microsim *PSpice*™. The Boyle macromodel (see Note 2) and subcircuit in Figure 54 are generated using the TLV246x typical electrical and operating characteristics at $T_A = 25^\circ\text{C}$. Using this information, output simulations of the following key parameters can be generated to a tolerance of 20% (in most cases):

- Maximum positive output voltage swing
- Maximum negative output voltage swing
- Slew rate
- Quiescent power dissipation
- Input bias current
- Open-loop voltage amplification
- Unity-gain frequency
- Common-mode rejection ratio
- Phase margin
- DC output resistance
- AC output resistance
- Short-circuit output current limit

NOTE 2: G. R. Boyle, B. M. Cohn, D. O. Pederson, and J. E. Solomon, "Macromodeling of Integrated Circuit Operational Amplifiers", *IEEE Journal of Solid-State Circuits*, SC-9, 353 (1974).

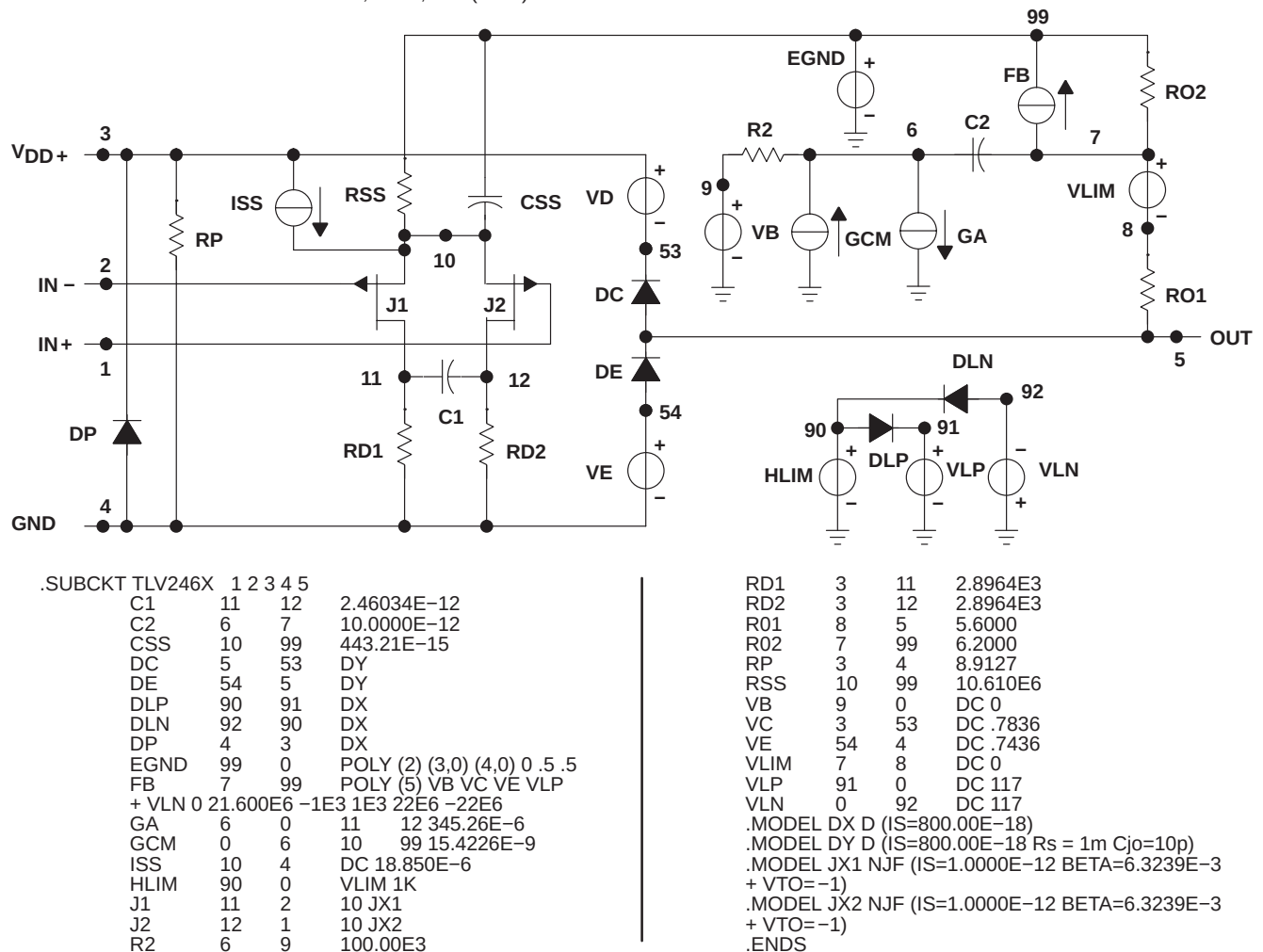


Figure 55. Boyle Macromodels and Subcircuit

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TLV2460A-EP TLV2461A-EP TLV2462A-EP TLV2463A-EP TLV2464A-EP

FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

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macromodel information (continued)

.subckt TLV_246Y 1 2 3 4 5 6	rp	3	71	8.9127
c1 11 12 2.4603E-12	rss	10	99	10.610E6
c2 72 7 10.000E-12	rs1	6	4	1G
css 10 99 443.21E-15	rs2	6	4	1G
dc 70 53 dy	rs3	6	4	1G
de 54 70 dy	rs4	6	4	1G
dlp 90 91 dx	s1	71	4	6 4 s1x
dln 92 90 dx	s2	70	5	6 4 s1x
dp 4 3 dx	s3	10	74	6 4 s1x
egnd 99 0 poly(2) (3,0) (4,0) 0 .5 .5	s4	74	4	6 4 s2x
fb 7 99 poly(5) vb vc ve vlp vln 0	vb	9	0	dc 0
21.600E6 -1E3 1E3 22E6 -22E6	vc	3	53	dc .7836
ga 72 0 11 12 345.26E-6	ve	54	4	dc .7436
gcm 0 72 10 99 15.422E-9	vlim	7	8	dc 0
iss 74 4 dc 18.850E-6	vlp	91	0	dc 117
hlim 90 0 vlim 1K	vln	0	92	dc 117
j1 11 2 10 jx1	.model dx D(Is=800.00E-18)			
j2 12 1 10 jx2	.model dy D(Is=800.00E-18 Rs=1m Cjo=10p)			
r2 72 9 100.00E3	.model jx1 NJF(Is=1.0000E-12 Beta=6.3239E-3 Vto=-1)			
rd1 3 11 2.8964E3	.model jx2 NJF(Is=1.0000E-12 Beta=6.3239E-3 Vto=-1)			
rd2 3 12 2.8964E3	.model s1x VSWITCH(Roff=1E8 Ron=1.0 Voff=2.5 Von=0.0)			
ro1 8 70 5.6000	.model s2x VSWITCH(Roff=1E8 Ron=1.0 Voff=0 Von=2.5)			
ro2 7 99 6.2000	.ends			

Figure 54. Boyle Macromodels and Subcircuit (Continued)

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLV2462AMDREP	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	2462AM	Samples
TLV2462AQDREP	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2462AE	Samples
TLV2464AMDREP	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	V2464AME	Samples
TLV2464AMDREPG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	V2464AME	Samples
TLV2464AMPWREP	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	2464AME	Samples
V62/03619-03XE	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2462AE	Samples
V62/03619-06XE	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	2462AM	Samples
V62/03619-07YE	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	V2464AME	Samples
V62/03619-07ZE	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	2464AME	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- ⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- ⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- ⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- ⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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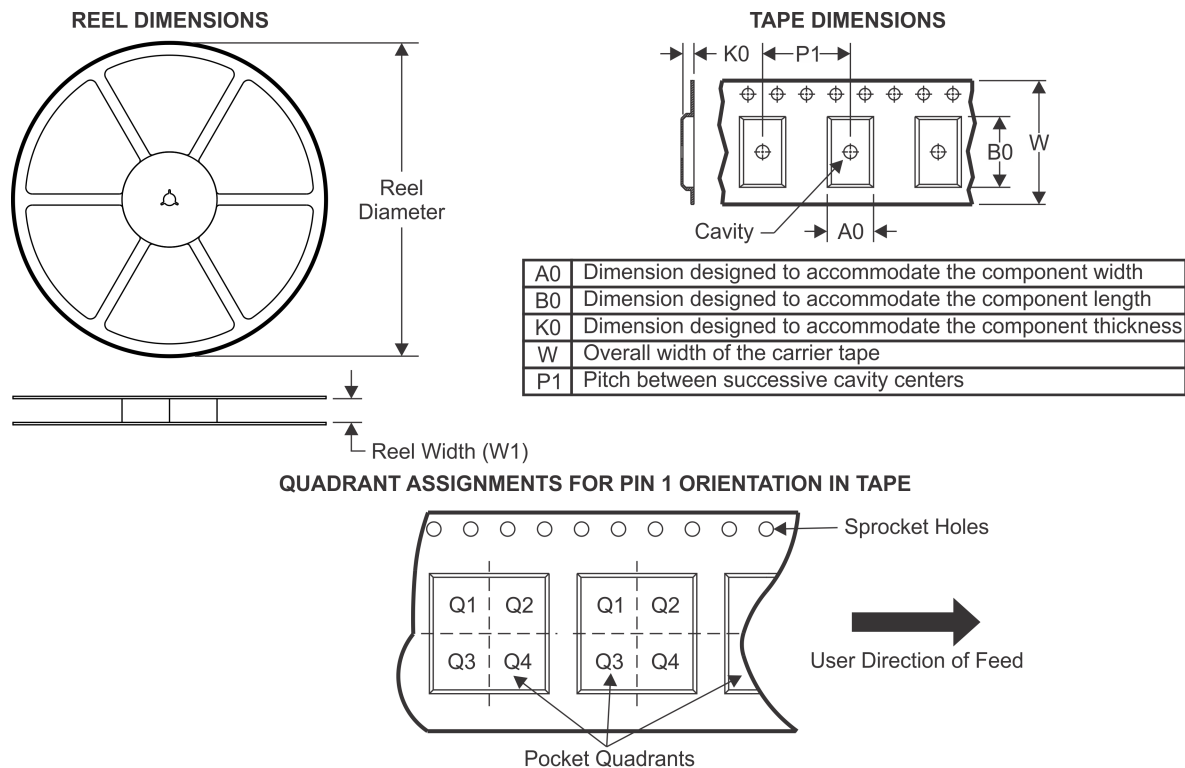
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OTHER QUALIFIED VERSIONS OF TLV2462A-EP, TLV2464A-EP :

- Catalog: [TLV2462A](#), [TLV2464A](#)
- Automotive: [TLV2462A-Q1](#), [TLV2464A-Q1](#)
- Military: [TLV2462AM](#)

NOTE: Qualified Version Definitions:

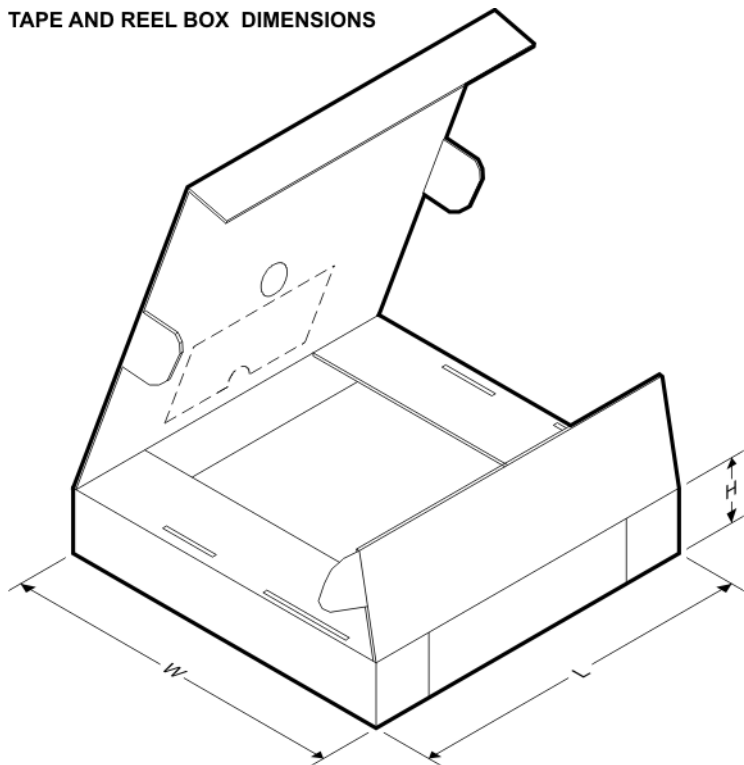
- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV2462AMDREP	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV2462AQDREP	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV2464AMDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLV2464AMPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV2462AMDREP	SOIC	D	8	2500	367.0	367.0	35.0
TLV2462AQDREP	SOIC	D	8	2500	367.0	367.0	35.0
TLV2464AMDREP	SOIC	D	14	2500	333.2	345.9	28.6
TLV2464AMPWREP	TSSOP	PW	14	2000	367.0	367.0	35.0

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